

**AMENDMENTS TO THE ABSTRACT**

Please amend the Abstract as follows:

A microelectronic imager having ~~comprising~~ an imaging unit and an optics unit attached to the imaging unit, and methods for packaging microelectronic imagers. In one embodiment, the imaging unit can include ~~[(a)]~~ a microelectronic die with an image sensor and a plurality of external contacts electrically coupled to the image sensor and ~~[(b)]~~ a first referencing element fixed to the imaging unit. The optics unit can include an optic member and a second referencing element fixed to the optics unit. The second referencing element is seated with the first referencing element at a fixed, preset position in which the optic member is situated at a desired location relative to the image sensor.